

英飞凌汽车级80V 175°C N沟道
增强型OptiMOS™ 5 功率晶体管

特点

- N沟道-增强模式
- 符合 AEC-Q100
- MSL1 回流焊峰值温度高达 260°C
- 工作温度 175°C
- 绿色产品：符合 RoHS 标准
- 超低 Rds(on)
- 100% 雪崩测试

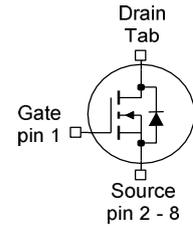
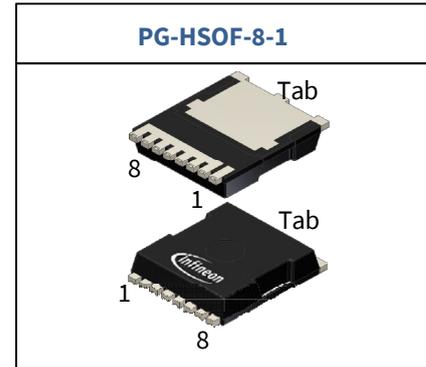
Type	Package	Marking
IAUT300N08S5N014	PG-HSOF-8-1	5N08014

除非另有规定，否则均为 $T_j=25\text{ °C}$ 的**最大额定值**。

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_c=25\text{ °C}, V_{GS}=10\text{V}^{(1)}$	300	A
		$T_c=100\text{ °C}, V_{GS}=10\text{V}^{(2)}$	230	
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_c=25\text{ °C}$	1200	
Avalanche energy, single pulse ²⁾	E_{AS}	$I_D=150\text{ A}$	600	mJ
Avalanche current, single pulse	I_{AS}	-	300	A
Gate source voltage	V_{GS}	-	± 20	V
Power dissipation	P_{tot}	$T_c=25\text{ °C}$	300	W
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	°C
IEC climatic category; DIN IEC 68-1	-	-	55/175/56	

产品概述

V_{DS}	80	V
$R_{DS(on)}$	1.4	mΩ
I_D	300	A



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Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

热特性²⁾

Thermal resistance, junction - case	R_{thJC}	-	-	-	0.5	K/W
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除非另有规定，否则均为 $T_j=25\text{ °C}$ 的**电气特性**。

静态参数特性

Drain-source breakdown voltage ²⁾	$V_{(BR)DSS}$	$V_{GS}=0\text{ V},$ $I_D=1\text{ mA}$	80	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=230\text{ }\mu\text{A}$	2.2	3	3.8	
Zero gate voltage drain current ²⁾	I_{DSS}	$V_{DS}=80\text{ V}, V_{GS}=0\text{ V},$ $T_j=25\text{ °C}$	-	0.1	1	μA
		$V_{DS}=40\text{ V}, V_{GS}=0\text{ V},$ $T_j=85\text{ °C}^{2)}$	-	1	20	
Gate-source leakage current	I_{GSS}	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=6\text{ V}, I_D=75\text{ A}$	-	1.6	2.1	m Ω
		$V_{GS}=10\text{ V}, I_D=100\text{ A}$	-	1.1	1.4	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

动态参数特性²⁾

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=40\text{ V},$ $f=1\text{ MHz}$	-	10137	13178	pF
Output capacitance	C_{oss}		-	1626	2114	
Reverse transfer capacitance	C_{rss}		-	71	106	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=40\text{ V}, V_{GS}=10\text{ V},$ $I_D=100\text{ A}, R_G=3.5\ \Omega$	-	25	-	ns
Rise time	t_r		-	15	-	
Turn-off delay time	$t_{d(off)}$		-	52	-	
Fall time	t_f		-	46	-	

栅极电荷特性²⁾

Gate to source charge	Q_{gs}	$V_{DD}=40\text{ V}, I_D=100\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	46	60	nC
Gate to drain charge	Q_{gd}		-	30	47	
Gate charge total	Q_g		-	144	187	
Gate plateau voltage	$V_{plateau}$		-	4.5	-	V

反向二极管

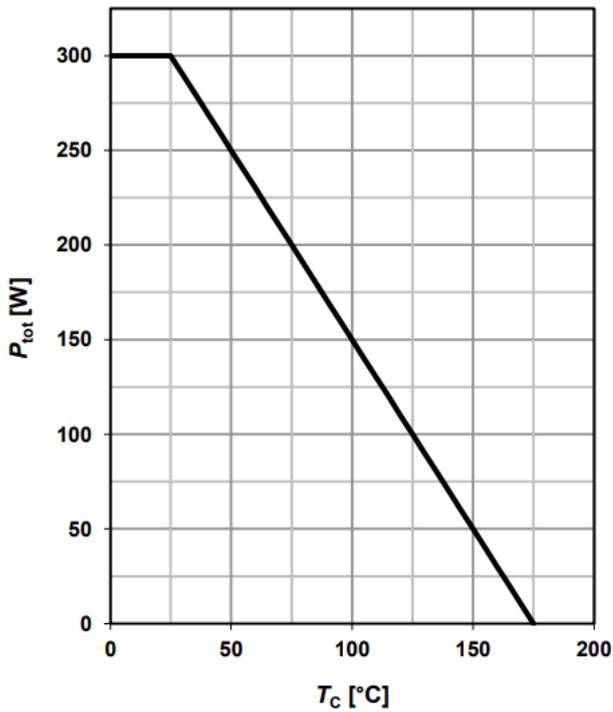
Diode continuous forward current ²⁾	I_S	$T_C=25\text{ }^\circ\text{C}$	-	-	300	A
Diode pulse current ²⁾	$I_{S,pulse}$		-	-	1200	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=100\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	0.9	1.2	V
Reverse recovery time ²⁾	t_{rr}	$V_R=40\text{ V}, I_F=50\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	83	-	ns
Reverse recovery charge ²⁾	Q_{rr}		-	156	-	nC

¹⁾ 电流受封装限制；当 $R_{thJC} = 0.5\text{ K/W}$ 时，该芯片在 25°C 时能够承载 327 A 。

²⁾ 由设计标定，不受制于生产测试。

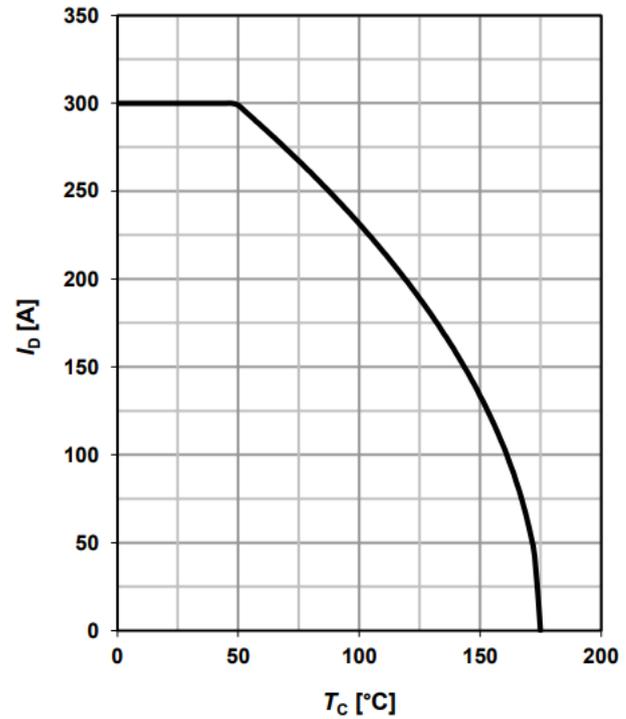
1 功率耗散

$$P_{\text{tot}} = f(T_c); V_{\text{GS}} \geq 6 \text{ V}$$



2 漏极电流

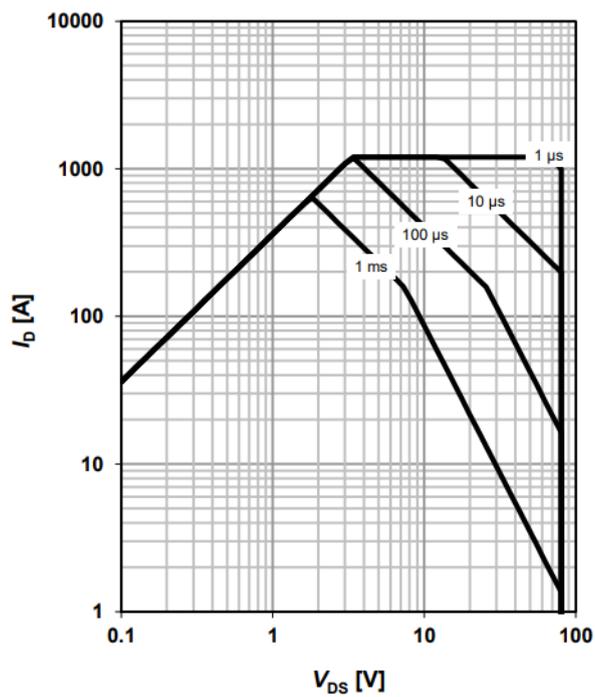
$$I_D = f(T_c); V_{\text{GS}} \geq 6 \text{ V}$$



3 安全工作区

$$I_D = f(V_{\text{DS}}); T_c = 25^\circ\text{C}; D = 0$$

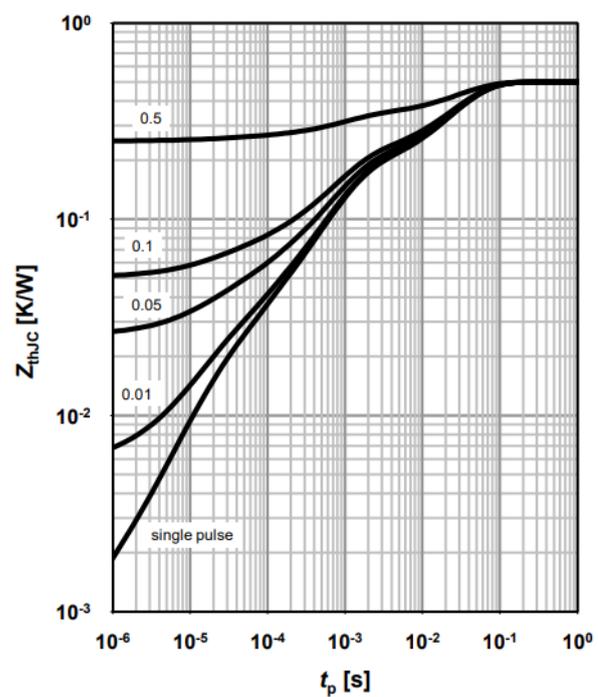
parameter: t_p



4 最大瞬态热阻抗

$$Z_{\text{thJC}} = f(t_p)$$

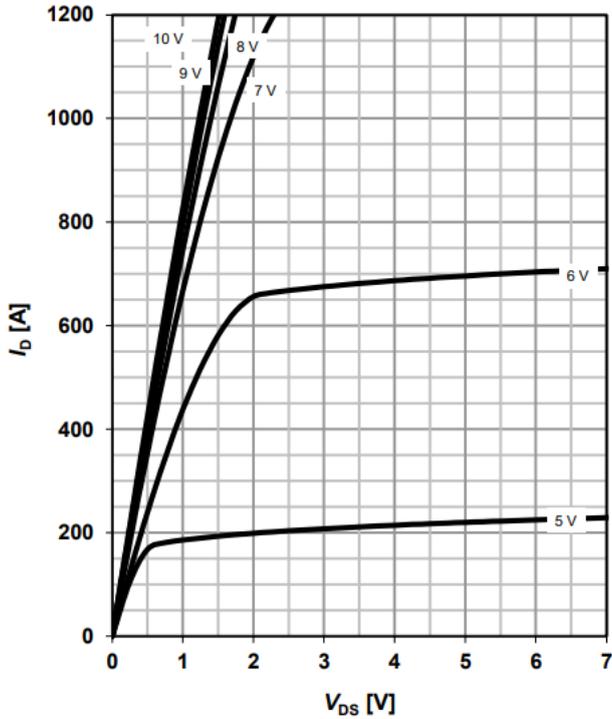
parameter: $D = t_p/T$



5 典型输出特性

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

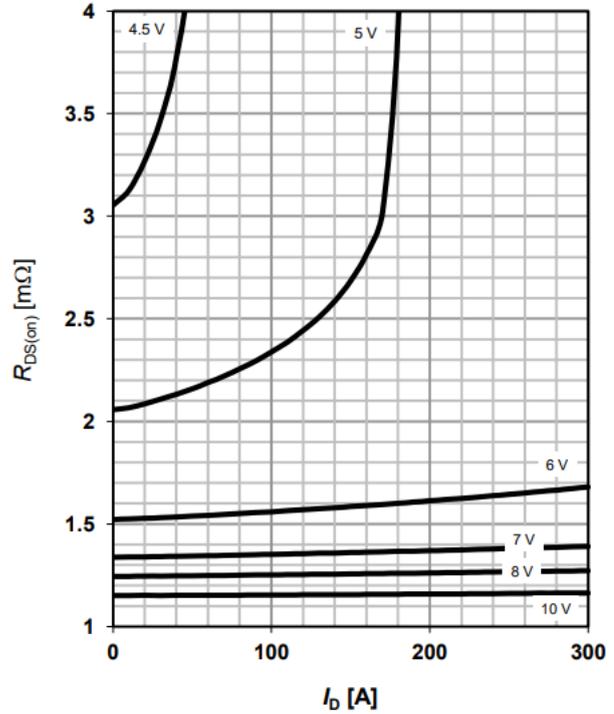
parameter: V_{GS}



6 典型漏源导通电阻

$$R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$$

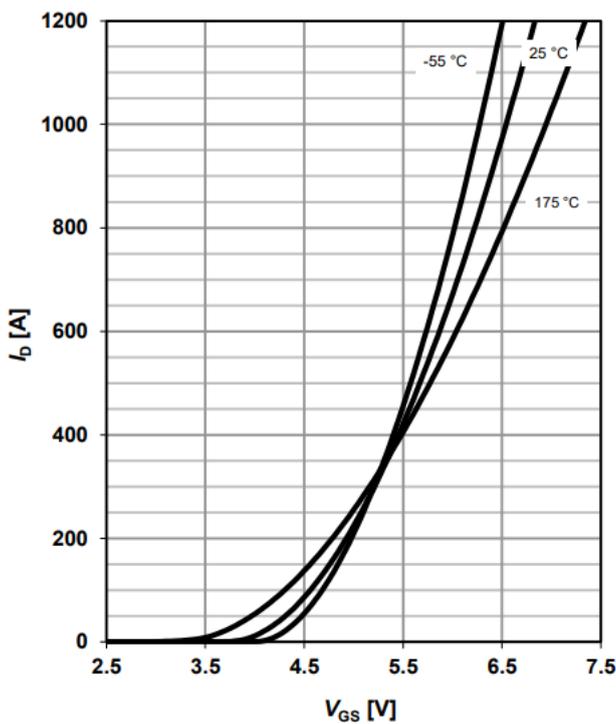
parameter: V_{GS}



7 典型转移特性

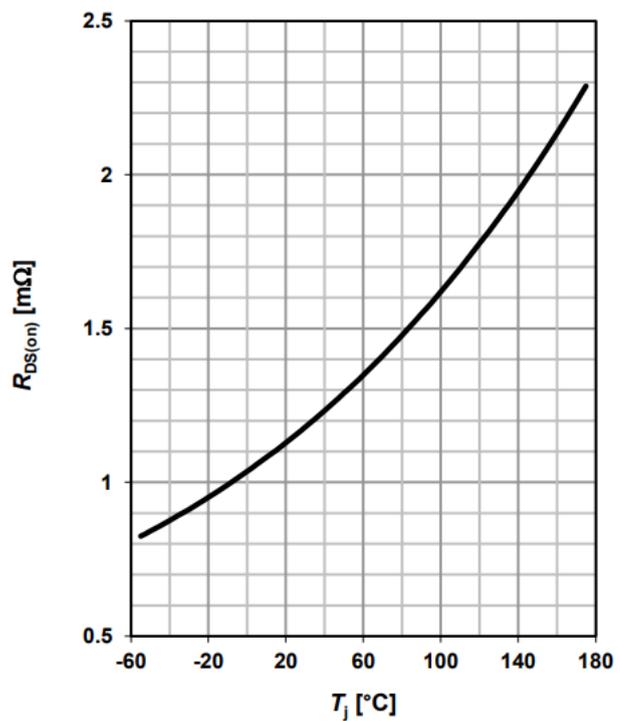
$$I_D = f(V_{GS}); V_{DS} = 6V$$

parameter: T_j



8 典型漏源导通电阻

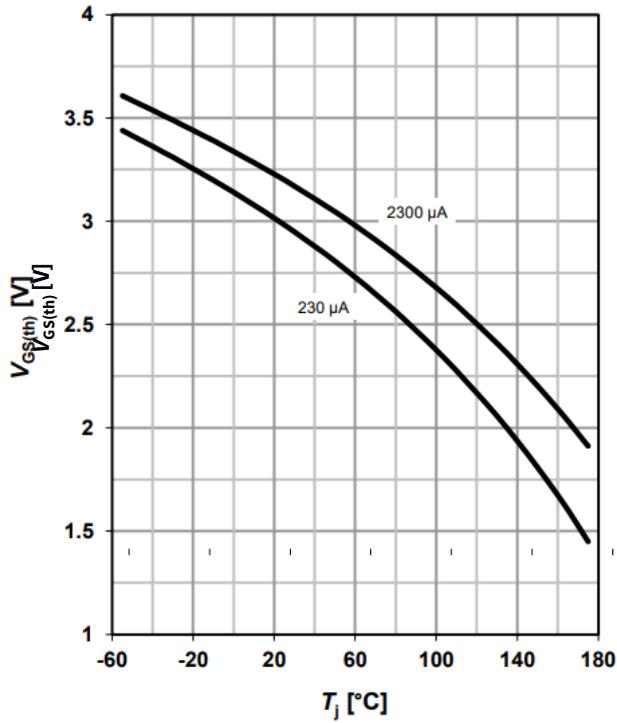
$$R_{DS(on)} = f(T_j); I_D = 100\text{ A}; V_{GS} = 10\text{ V}$$



9 典型栅极阈值电压

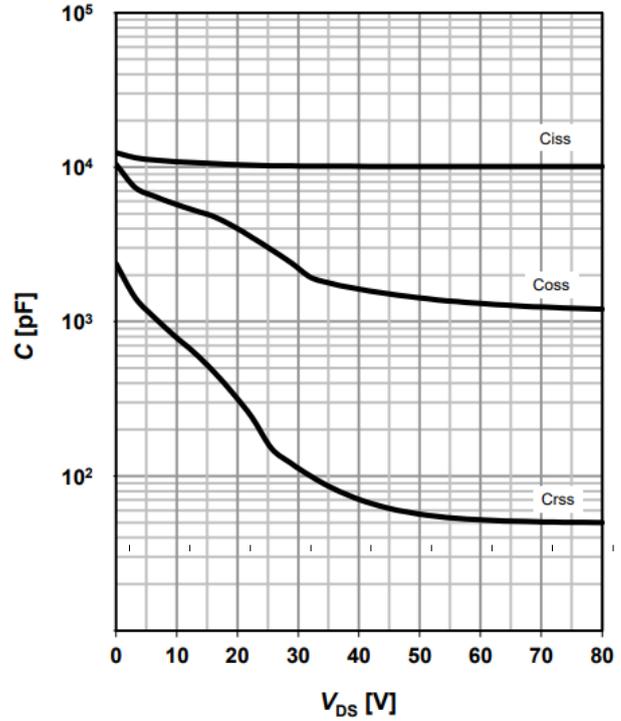
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

parameter: I_D



10 典型电容值

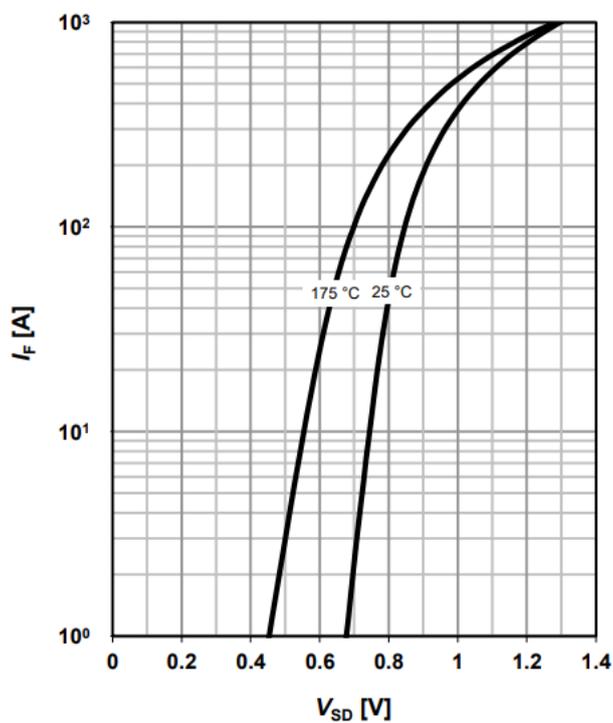
$$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$$



11 典型二极管正向导通特性

$$I_F = f(V_{SD})$$

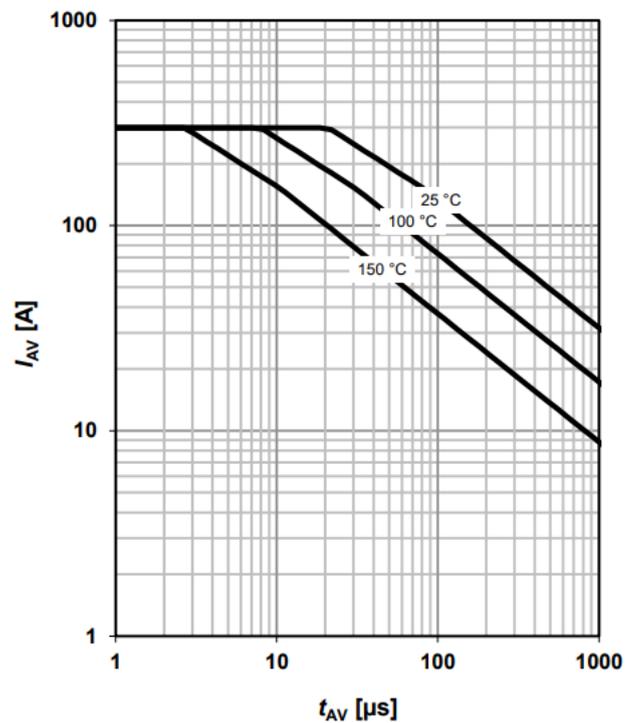
parameter: T_j



12 典型雪崩特性

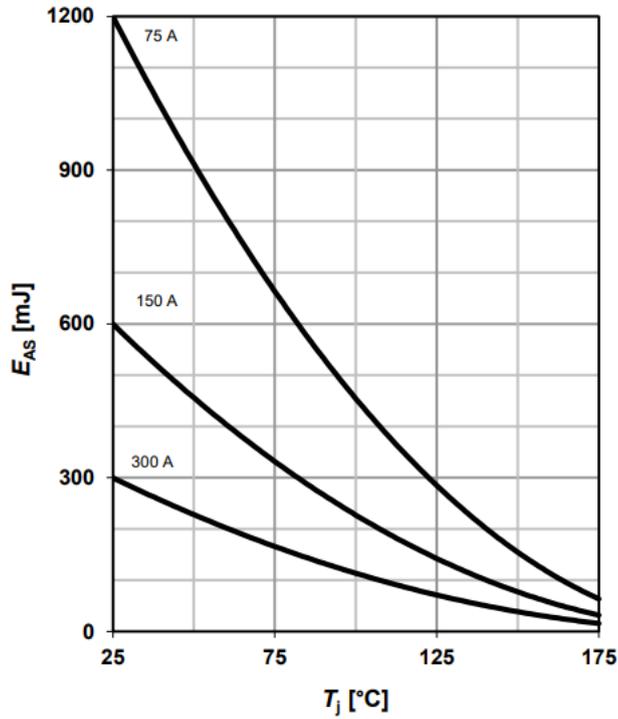
$$I_{AS} = f(t_{AV})$$

parameter: $T_{j(start)}$

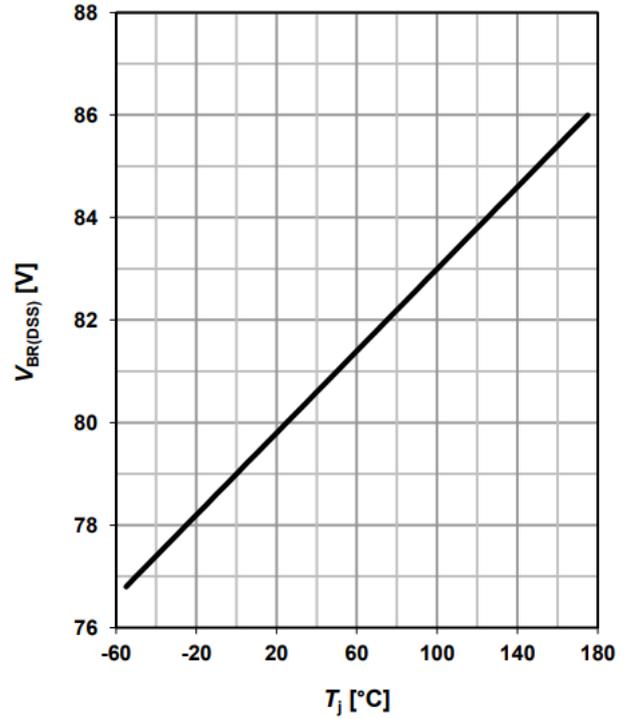


13 典型雪崩能量

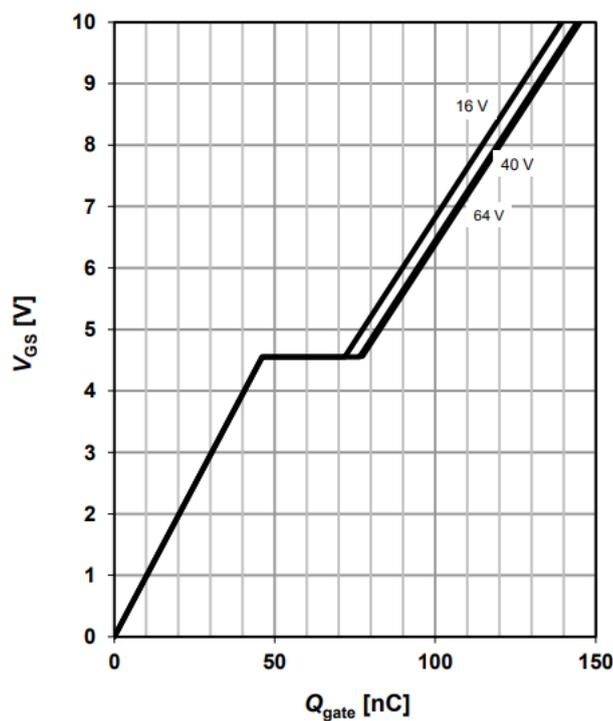
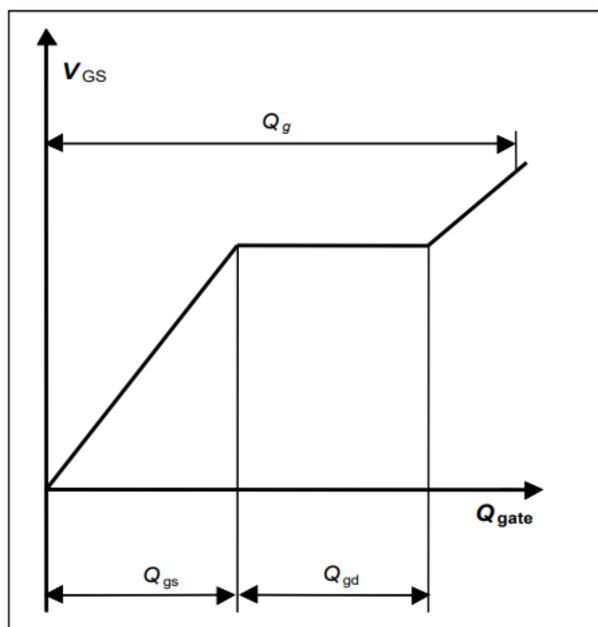
$$E_{AS} = f(T_j)$$

 parameter: I_D

14 漏源击穿电压

$$V_{BR(DSS)} = f(T_j); I_{D_typ} = 1 \text{ mA}$$


15 典型栅极电荷

$$V_{GS} = f(Q_{gate}); I_D = 100 \text{ A pulsed}$$

 parameter: V_{DD}

16 栅极充电波形


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修订记录

Version	Date	Changes
Version 1.0	15.12.2017	Final Data Sheet
Version 1.1	17.01.2024	package name (page 1)



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